

Table of Contents

Preface and Committees

Chapter 1: Development and Prototyping

Method for the Identification and Comparison of Alternative Process Chains Focusing on Economics Efficiency Analysis during the Conceptual Design of Mechatronic Integrated Devices	
T. Schierbaum, J. Gausemeier and R. Dumitrescu	3
Novel Approach for the Implementation of 3D-MID Compatible Routing Functionalities into Computer-Aided Design Tools	
J. Zeitler, B. Götz, C. Fischer and J. Franke	11
Optimized Process Sequences for Prototyping of Molded Interconnect Devices	
C. Jürgenhake, C. Fechtelpeter, R. Dumitrescu and D. Heidsiek	19
Integration of Functional Circuits into FDM Parts	
A. Wild	29

Chapter 2: Printing Technologies

Printing of Functional Structures on Molded 3D Devices	
B. Polzinger, V. Matic, L. Liedtke, J. Keck, D. Hera, T. Günther, W. Eberhardt and H. Kück	37
Electrical Functionalization of Thermoplastics by Combining Plasmadust Coating and Aerosol Jet Printing	
R. Schramm, J. Hörber, C. Dold and J. Franke	43
Production of Miniaturized Sensor Structures on Polymer Substrates Using Inkjet Printing	
O. Kravchuk, K. Grunewald, J. Bahr, F. Hofmann and M. Reichenberger	49
Progress in the Manufacturing of Molded Interconnected Devices by 3D Microcontact Printing	
K. Cheval, J. Coulm, S. Gout, Y. Layouni, P. Lombard, D. Leonard, F. Bessueille, V. Semet and M. Cabrera	57

Chapter 3: Materials and Manufacturing

Characterization of Electromagnetic Properties of MID Materials for High Frequency Applications up to 67 GHz	
Q.H. Dao, A. Friedrich and B. Geck	63
Novel Laser Induced Metallization for Three Dimensional Molded Interconnect Device Applications by Spray Method	
M.C. Chou, T.H. Kao, M.C. Huang, W.H. Zhang, W.Y. Li and T.H. Lai	69
Experimental Investigation of Laser Sintering of Conductive Adhesive for Functional Prototypes Produced by Embedding Stereolithography	
B. Niese, P. Amend, U. Urmoneit, S. Roth and M. Schmidt	75
MID Fabricated by Ultrasonic Processing	
W.K. Schomburg, J. Li, S. Liao, C. Gerhardy and J. Sackmann	83
Usage of Industrial Robots as Flexible Handling Devices Supporting the Process of Three Dimensional Conductive Pattern Generation	
A. Buschhaus and J. Franke	89

Chapter 4: Manufacturing Processes

Study of MID Technologies for Automotive Lighting and Light Signaling Devices	
F. Marcori, M. Antonipieri, I. di Vora, S. Padovani and I. Rioli	97

Chapter 5: Assembly Technologies and Inspection

Design and Solder Process Optimization in MID Technology for High Power Applications

A. Syed-Khaja and J. Franke

107

Chapter 6: Quality and Reliability

Hot Pin Pull Method – New Test Procedure for the Adhesion Measurement for 3D-MID

C. Goth, T. Kuhn, G. Gion and J. Franke

115